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(12) **United States Design Patent**
Nguyen

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(54) **WAFER POLISHING PAD HOLDER**

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(**) Term: **14 Years**

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(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182; 257/E21, 21, E21.23; 361/234;
451/72, 285, 286, 287, 288
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a wafer polishing pad holder, as shown and described.

DESCRIPTION

FIG. 1 is a top perspective view of the wafer polishing pad holder showing my new design;

FIG. 2 is a top view of the wafer polishing pad holder showing my new design;

FIG. 3 is a front view of the wafer polishing pad holder showing my new design;

FIG. 4 is a rear view of the wafer polishing pad holder showing my new design;

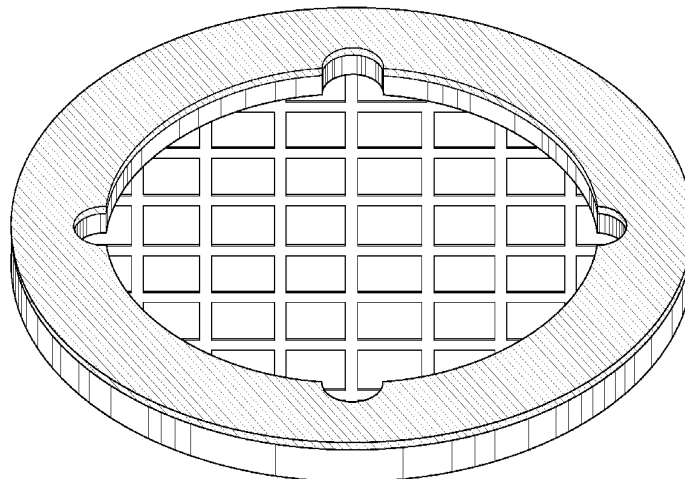
FIG. 5 is a right side view of the wafer polishing pad holder showing my new design;

FIG. 6 is a left side view of the wafer polishing pad holder showing my new design; and

FIG. 7 is a cross sectional view of the wafer polishing pad holder, taken from FIG. 2 as indicated showing my new design; and,

FIG. 8 is a top view of the wafer polishing pad holder without the milled island within the inside pocket showing my new design.

1 Claim, 8 Drawing Sheets



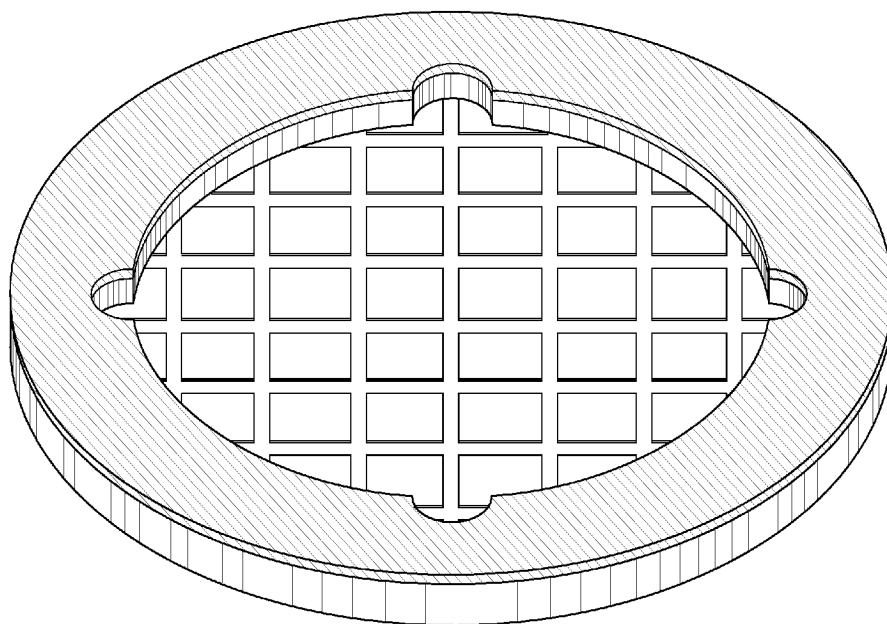


FIG. 1

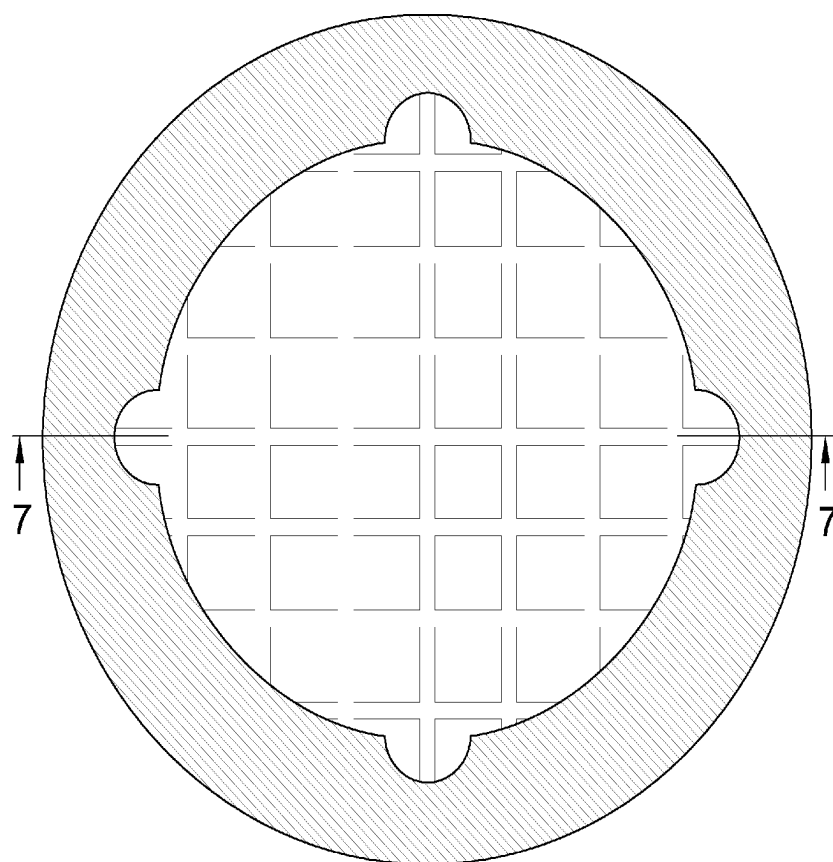


FIG. 2



FIG. 3



FIG. 4



FIG. 5

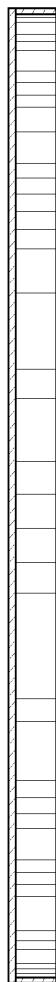


FIG. 6



FIG. 7

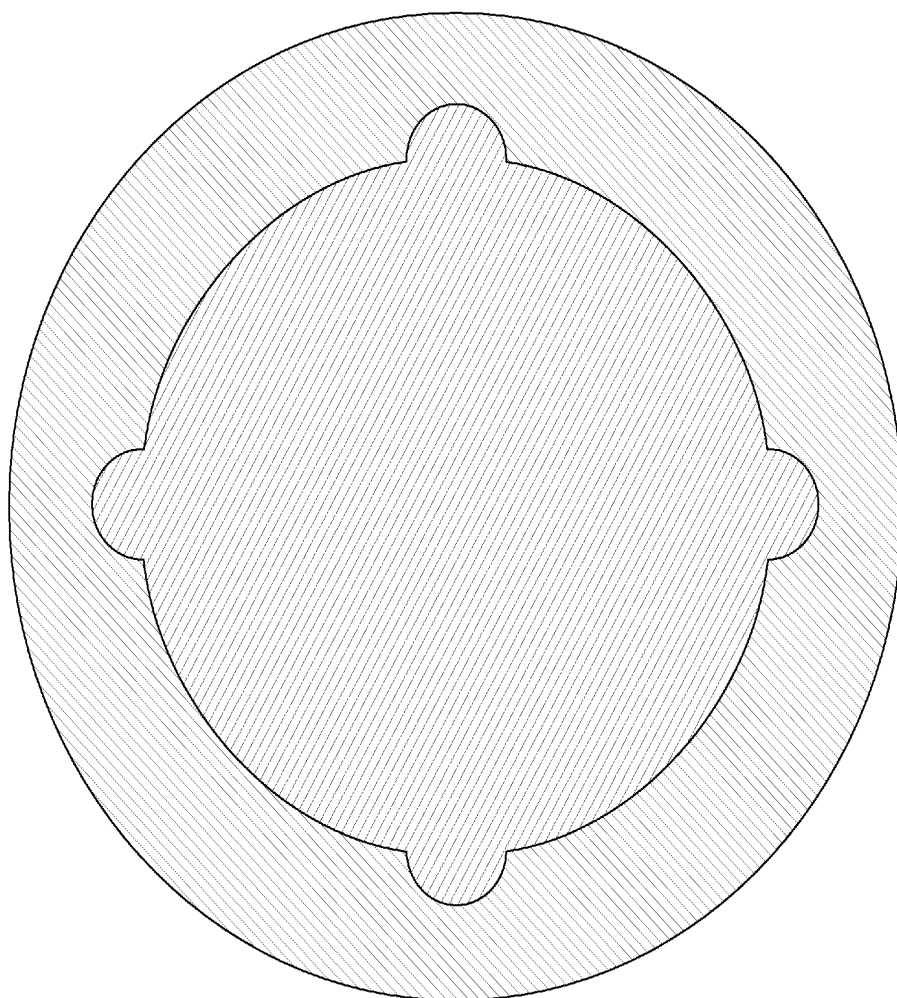


FIG. 8